

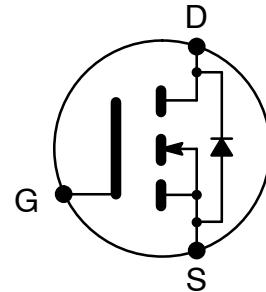


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**NTE2968**  
**MOSFET**  
**N-Channel, Enhancement Mode**  
**High Speed Switch**  
**TO3P Type Package**

**Features:**

- Avalanche Rugged Technology
- Rugged Gate Oxide Technology
- Low Input Capacitance
- Improved Gate Charge
- Extended Safe Operating Area
- Lower Leakage Current
- Low Static Drain-Source On-State Resistance



**Absolute Maximum Ratings:**

Drain-Source Voltage, $V_{DSS}$ .....	200V
Drain Current, $I_D$ Continuous	
$T_C = +25^\circ\text{C}$ .....	45A
$T_C = +100^\circ\text{C}$ .....	27.8A
Pulsed (Note 1) .....	180A
Gate-Source Voltage, $V_{GS}$ .....	$\pm 30\text{V}$
Gate Current (Pulsed), $I_{GM}$ .....	$\pm 1.5\text{A}$
Single Pulsed Avalanche Energy (Note 2), $E_{AS}$ .....	675mJ
Avalanche Current (Note 1), $I_{AS}$ .....	45A
Repetitive Avalanche Energy (Note 1), $E_{AR}$ .....	27.8mJ
Peak Diode Recovery $dv/dt$ (Note 3), $dv/dt$ .....	5.0V/ns
Total Power Dissipation ( $T_C = +25^\circ\text{C}$ ), $P_D$ .....	278W
Derate Above $25^\circ\text{C}$ .....	$2.22\text{W}/^\circ\text{C}$
Operating Junction Temperature Range, $T_J$ .....	$-55^\circ$ to $+150^\circ\text{C}$
Storage Temperature Range, $T_{stg}$ .....	$-55^\circ$ to $+150^\circ\text{C}$
Maximum Lead Temperature (During Soldering, 1/8" from case, 5sec), $T_L$ .....	$+300^\circ\text{C}$
Thermal Resistance:	
Maximum Junction-to-Case, $R_{thJC}$ .....	$0.45^\circ\text{C}/\text{W}$
Typical Case-to-Sink, $R_{thCS}$ .....	$0.24^\circ\text{C}/\text{W}$
Maximum Junction-to-Ambient, $R_{thJA}$ .....	$40^\circ\text{C}/\text{W}$

Note 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Note 2.  $L = 0.5\text{mH}$ ,  $I_{AS} = 45\text{A}$ ,  $V_{DD} = 25\text{V}$ ,  $R_G = 25\pm$ , Starting  $T_J = +25^\circ\text{C}$ .

Note 3.  $I_{SD} \leq 45\text{A}$ ,  $di/dt \leq 370\text{A}/\text{s}$ ,  $V_{DD} \leq BV_{DSS}$ , Starting  $T_J = +25^\circ\text{C}$ .

**Electrical Characteristics:** ( $T_C = +25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}$ , $I_D = 250\text{mA}$	200	-	-	V
Breakdown Voltage Temperature Coefficient	$\Delta \text{BV}/\Delta T_J$	$I_D = 250\text{mA}$	-	0.20	-	$\text{V}/^\circ\text{C}$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = 5\text{V}$ , $I_D = 250\text{mA}$	2.0	-	4.0	V
Gate-Source Leakage Forward	$I_{\text{GSS}}$	$V_{\text{GS}} = 30\text{V}$	-	-	100	nA
Gate-Source Leakage Reverse	$I_{\text{GSS}}$	$V_{\text{GS}} = -30\text{V}$	-	-	-100	nA
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 200\text{V}$ , $V_{\text{GS}} = 0$	-	-	10	$\text{mA}$
		$V_{\text{DS}} = 160\text{V}$ , $T_C = +150^\circ\text{C}$	-	-	100	$\text{mA}$
Static Drain-Source ON Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}$ , $I_D = 22.5\text{A}$ , Note 4	-	-	0.065	$\pm$
Forward Transconductance	$g_{\text{fs}}$	$V_{\text{DS}} = 40\text{V}$ , $I_D = 22.5\text{A}$ , Note 4	-	25.06	-	mhos
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V}$ , $V_{\text{DS}} = 25\text{V}$ , $f = 1\text{MHz}$	-	3030	3940	pF
Output Capacitance	$C_{\text{oss}}$		-	530	610	pF
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	255	295	pF
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 100\text{V}$ , $I_D = 45\text{A}$ , $R_G = 5.3\pm$ , Note 4, Note 5	-	22	60	ns
Rise Time	$t_r$		-	22	60	ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	79	170	ns
Fall Time	$t_f$		-	36	80	ns
Total Gate Charge	$Q_g$	$V_{\text{GS}} = 10\text{V}$ , $I_D = 45\text{A}$ , $V_{\text{DS}} = 160\text{V}$ , Note 4, Note 5	-	117	152	nC
Gate-Source Charge	$Q_{\text{gs}}$		-	25	-	nC
Gate-Drain ("Miller") Charge	$Q_{\text{gd}}$		-	48.8	-	nC

**Source-Drain Diode Ratings and Characteristics**

Continuous Source Current	$I_S$	(Body Diode)	-	-	45	A
Pulse Source Current	$I_{\text{SM}}$	(Body Diode) Note 1	-	-	180	A
Diode Forward Voltage	$V_{\text{SD}}$	$T_J = +25^\circ\text{C}$ , $I_S = 45\text{A}$ , $V_{\text{GS}} = 0\text{V}$ , Note 4	-	-	1.5	V
Reverse Recovery Time	$t_{\text{rr}}$	$T_J = +25^\circ\text{C}$ , $I_F = 45\text{A}$ , $dI_F/dt = 100\text{A}/\mu\text{s}$	-	210	-	ns
Reverse Recovery Charge	$Q_{\text{rr}}$		-	1.67	-	$\mu\text{C}$

Note 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Note 4. Pulse Test: Pulse Width  $\leq 250\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .

Note 5. Essentially independent of operating temperature.

